

(12) United States Patent Howell

(54) SYSTEM AND METHOD FOR ANALYZING ELECTRONIC DEVICES HAVING OPPOSING THERMAL COMPONENTS

(71) Applicant: **Exatron, Inc.**, San Jose, CA (US)

Inventor: Robert P. Howell, San Jose, CA (US)

Assignee: Exatron, Inc., San Jose, CA (US)

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See application file for complete search history.

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Primary Examiner — Minh N Tang (74) Attorney, Agent, or Firm — Stephen M. De Klerk

ABSTRACT (57)

A system for analyzing electronic devices is described. An input station receives a plurality of electronic devices. A pick-and-place transport apparatus having a pick up tip for engaging and transporting one of the electronic devices at a time from the input station to the electric machine interface station, disengaging from the electronic device, and moving away from the electronic device The pick up tip is movable for engaging the electronic device while at the electric machine interface station and transporting the electronic device away from the electric machine interface station to disengage the electronic devices from the electric machine interface. First and second thermal devices secured to the support structure on opposing sides of the electronic device when the electronic device is at the electric machine interface station to simultaneously transfer heat to or form the electronic device.

15 Claims, 6 Drawing Sheets

